

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	JONATHAN ZHAN HUA LEONG	11/28/2017
	YING-HUNG CHEN	11/29/2017
	TSUNG-CHIH TSAI	11/29/2017
RECEIVING PARTY DATA		
Name:	STYLEME LIMITED	
Street Address:	SUITES 1-3, 16TH F	
Internal Address:	KINWICK CENTRE 32 HOLLYWOOD RD., CENTRAL	
City:	HONG KONG	
State/Country:	HONG KONG	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	15806256	
CORRESPONDENCE DATA		
Fax Number:	(650)847-4151	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	650 847 4150	
Email:	idocketing@duanemorris.com	
Correspondent Name:	DUANE MORRIS LLP (MANITA-GENERAL) IP DOC	
Address Line 1:	2475 HANOVER STREET	
Address Line 4:	PALO ALTO, CALIFORNIA 94304-1194	
ATTORNEY DOCKET NUMBER:	70840-00004	
NAME OF SUBMITTER:	MANITA RAWAT	
SIGNATURE:	/Manita Rawat/	
DATE SIGNED:	11/29/2017	
Total Attachments: 2		
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ASSIGNMENT OF APPLICATION FOR PATENT

WHEREAS, Jonathan Zhan Hua LEONG of 13 F No. 107, Songguin St. Xinyi District, Taipei, 11047, Taiwan, China, Ying-Hung CHEN of 17991 Darmel Place, Santa Ana, California, 92705 United States, and Tsung-Chih TSAI of 3F., No.7-1, Aly. 3, Ln. 16, Dafeng Rd., Xindian Dist., New Taipei City 231, Taiwan, are the inventors of an invention entitled **PHYSICS BASED GARMENT SIMULATION SYSTEMS AND METHODS** that is the subject matter of: (check all that apply)

- ☐ a provisional application for Letters Patent which is identifiable in the United States Patent and Trademark Office by Application No. _____ filed on _____;
- ☒ an application for Letters Patent which is identifiable in the United States Patent and Trademark Office by Application No. 15/806,256 filed on November 7, 2017 and/or executed on even date herewith; and
- ☐ an international application for Letters Patent filed pursuant to the Patent Cooperation Treaty which is identifiable in the United States Receiving Office by Application No. _____ filed on _____; and/or executed on even date herewith:

WHEREAS

STYLEME LIMITED, a corporation having a business address of
Suites 1-3, 16th F, Kinwick Centre 32 Hollywood Rd., Central, Hong Kong

and which, together with its successors, assigns, and legal representatives, is hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in, to and under said invention and in, to and under Letters Patent or similar legal protection to be obtained therefore in the United States and in any and all foreign countries.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

Be it known that for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE, the full and exclusive right, title and interest to said discovery or invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in any and all foreign countries to be obtained for said invention by said application or any continuation, continuation-in-part, divisional, reexamination, renewal, substitute, reissue and/or any application claiming priority thereof, including any legal equivalent thereof, in a foreign country for the full term or terms for which the same may be granted.

I, SAID ASSIGNOR, hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and any Official of any country or countries foreign to the United States of America whose duty it is to issue Letters Patent on applications as aforesaid, to issue all such Letters Patent for said discovery or invention to the ASSIGNEE, as assignee of the entire right, title and interest in, to and under the same, for the sole use and benefit of the ASSIGNEE in accordance with the terms of this instrument.

I, SAID ASSIGNOR, hereby covenant with ASSIGNEE that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned and that I have full right to convey the entire right, title and interest herein sold, assigned, transferred and set over.

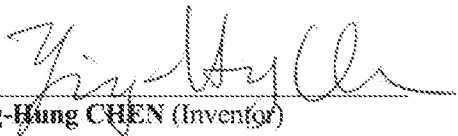
AND I, SAID ASSIGNOR, hereby further covenant and agree that the ASSIGNEE may apply for foreign Letters Patent on said discovery or invention and claim the benefits of the International Convention, and that I will, at any time, when called upon to do so by the ASSIGNEE communicate to the ASSIGNEE as the case may be, any facts known to me respecting said discovery or invention, and execute and deliver any and all lawful papers that may be necessary or desirable to perfect the title to the said discovery or invention, the said applications and the said Letters Patent in the ASSIGNEE and that if reissues or reexaminations of the said Letters Patent or disclaimers relating thereto, or divisionals, continuations, continuation-in-parts of the said applications shall hereafter be desired by the ASSIGNEE, I will, at any time, when called upon to do so by the ASSIGNEE sign all lawful papers, make all rightful oaths, execute and deliver all such disclaimers and all divisional, continuation, continuation-in-part, reexamination, and reissue applications so desired, and do all lawful acts requisite for the application for such continuations, continuation-in-parts, divisionals, reexaminations, or reissues and the procuring thereof and for the filing of such disclaimers and such applications, and generally do everything possible to aid the ASSIGNEE to obtain and enforce proper patent protection for said invention or discovery in all countries, all without further compensation but at the expense of the ASSIGNEE.

Inventors: Please Sign and Date Below:



Jonathan Zhan Hua LEONG (Inventor)

Date: 2017.11.28



Ying-Hung CHEN (Inventor)

Date: 2017.11.29

Tsung-Chih TSAI (Inventor)

Date: Tsung-chih Tsai 2017.11.29